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SEK 18 male low profile solder and press-in RoHS compliant				Recommended configuration of plated through holes for press-in termination In addition to the hot-air-level (HAL), other PCB surfaces are getting more important. Due to their different properties – such as mechanical strength and coefficient of friction – we recommend the following configuration of PCB through holes. <table><tr><td rowspan="3">Tin plated PCB (HAL) acc. to EN 60352-5</td><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td>Sn</td><td>max. 15 µm</td></tr><tr><td rowspan="3">Chemical tin plated PCB</td><td>plated hole Ø</td><td>0,94 - 1,09 mm</td></tr><tr><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td rowspan="3">Gold /Nickel plated PCB</td><td>Sn</td><td>min. 0,8µm</td></tr><tr><td>plated hole Ø</td><td>1,00 - 1,10 mm</td></tr><tr><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td rowspan="3">Silver plated PCB</td><td>Cu</td><td>min. 25 µm</td></tr><tr><td>Ag</td><td>0,1 - 0,3 µm</td></tr><tr><td>plated hole Ø</td><td>1,00 - 1,10 mm</td></tr><tr><td rowspan="3">Copper plated PCB (OSP)</td><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td>plated hole Ø</td><td>1,00 - 1,10 mm</td></tr></table>				Tin plated PCB (HAL) acc. to EN 60352-5	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	Sn	max. 15 µm	Chemical tin plated PCB	plated hole Ø	0,94 - 1,09 mm	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	Gold /Nickel plated PCB	Sn	min. 0,8µm	plated hole Ø	1,00 - 1,10 mm	Drilled hole Ø	1,15-0,03 mm	Silver plated PCB	Cu	min. 25 µm	Ag	0,1 - 0,3 µm	plated hole Ø	1,00 - 1,10 mm	Copper plated PCB (OSP)	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	plated hole Ø	1,00 - 1,10 mm																																																									
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All Dimensions in mm Original Size DIN A3 All rights reserved Department EC PD – DE HARTING Electronics GmbH D-32339 Espelkamp Scale 1:1 Free size tol. Created by STORCK Inspected by LEHNERT Standardisation HOFFMANN Date 2016-09-05 State Final Release Title SEK 18 male low profile solder and press-in Doc-Key / ECM-Nr. 100554984/UGD/001/F 500000107692 Type DS Number 09181100001 Rev. F Page 1/1																																																																																																			
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Как с нами связаться

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